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OCT 1 2 2006

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

|    | In Re Application of:        | ) | •                           |
|----|------------------------------|---|-----------------------------|
|    |                              | ) |                             |
| 5  | LIN ET AL.                   | ) | Examiner: MITCHELL, JAMES M |
|    |                              | ) |                             |
|    | Serial No.: 10/055,560       | ) | Art Unit: 2813              |
|    | •                            | ) |                             |
|    | Filed: January 22, 2002      | ) | Docket No.: MEGP0009USA     |
| 10 |                              | ) |                             |
|    | For: INTEGRATED CHIP PACKAGE | ) |                             |
|    | STRUCTURE USING METAL        | ) |                             |
|    | SUBSTRATE AND METHOD OF      | ) |                             |
|    | MANUFACTURING THE SAME       | ) |                             |
| 15 |                              |   |                             |

#### RESPONSE TO OFFICE ACTION

## 20 Mail Stop AF

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

### 25 Dear Sir:

The Office Action mailed Jul. 13, 2006 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

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